Korean International Semiconductor Conference & Exhibition
on Manufacturing Technology 2025

KISM 2025 BUSAN

Re:Innovation of Semiconductor Manufacturing for AI Ecosystem

[ThE1] CMP for Heterogeneous Integration and New Materials

Session Date	November 13 (Thu.), 2025
Session Time	09:00-10:45
Session Room	Room E (Sicily Room, 1F)
Session Chair	Prof. Kangchun Lee (Kwangwoon Univ., Korea)

[ThE1-1] [Plenary] **09:00-09:45**

Role of CMP in Enabling New Materials for Heterogeneous Integration

K. Mikhaylichenko, C. Lee, T. Osterheld, S. Barkam, S. Deshpande, B. Brown, R. Sreenivasan, S. Krishnan, M. Khoury, J. Lei, Z. Chen, K. Sharma, B. Chen, and V. Sukumaran (Applied Materials, USA)

[ThE1-2] [Invited] **09:45-10:15**

Oxide Layer Engineering for Cobalt CMP

Taeseup Song, Ungyu Paik, Ganggyu Lee, Sumin Hong, and Giha Lee (Hanyang Univ., Korea)

[ThE1-3] [Invited] **10:15-10:45**

Hybrid Bonding Challenges and Advanced CMP Strategies for Yield Enhancement

Haeri Kim, Hyeok Joo Lee, Sangchul Kim, and Jong Han Shin (SK hynix Inc., Korea)